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Serial No. 10/782,455
Art Unit: 2831 Examiner: Anton B. Harris
IBM Docket: AUS920031049US1(4037)

1-32 (Cancelled)

33. (Previously Presented) An enclosure for an electronic device, the enclosure comprising:
an interior surface and an outside surface of the enclosure, the interior surface enclosing the electronic device;
mounting sites to mount integrated circuits, wherein the mounting sites couple with the interior surface;
a pattern of interconnects coupled with the interior surface and interconnected with the mounting sites to transmit signals between the integrated circuits; and
at least one switch coupled with the pattern of interconnects at the interior surface and exposed via the outside surface of the enclosure to receive input from outside of the enclosure.
34. (Previously Presented) The enclosure of claim 33, further comprising other components coupled with the pattern of interconnects via the mounting sites.
35. (Previously Presented) The enclosure of claim 34, wherein the at least one switch comprises an optical switch to toggle in response to a change in light sensed by the optical switch.
36. (Previously Presented) The enclosure of claim 34, wherein the at least one switch comprises a pressure-sensitive switch coupled with the pattern of interconnects via one of the mounts.
37. (Previously Presented) The enclosure of claim 33, wherein the pattern of interconnects comprises a conductive paint applied directly to the enclosure, wherein the enclosure is composed of a substantially non-conductive plastic.

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38. (Previously Presented) The enclosure of claim 37, wherein the enclosure is composed of a pliable material.
39. (Previously Presented) The enclosure of claim 33, wherein the pattern of interconnects is coupled with the enclosure via at least one layer of non-conductive laminates.
40. (Previously Presented) The enclosure of claim 33, wherein the pattern of interconnects applied to an interior surface of the enclosure comprises a layer of metal having portions etched away to reveal the pattern of interconnects.
41. (Previously Presented) A system comprising:
 an enclosure comprising an interior surface and an outside surface, the interior surface enclosing an electronic device;
 integrated circuits;
 mounts in the enclosure to mount the integrated circuits, wherein the mounts couple with the interior surface;
 a pattern of interconnects coupled with the interior surface and interconnected with the mounts to transmit signals between the integrated circuits; and
 at least one switch coupled with the pattern of interconnects and exposed via the outside surface of the enclosure to receive input from outside of the system.
42. (Previously Presented) The system of claim 41, further comprising sensors to sense environmental conditions, the sensors being oriented to face the exterior of the enclosure.
43. (Previously Presented) The system of claim 41, wherein the pattern of interconnects resides on a laminate, the laminate being adhered to the interior surface of the enclosure.
44. (Previously Presented) The system of claim 41, wherein the pattern of interconnects is coupled with a circuit board internal of the enclosure to communicatively couple the integrated circuits with other components mounted to the circuit board.

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45-52 (Withdrawn)

53. (New) An apparatus comprising:
- an enclosure comprising an interior surface to enclose a device and an outside surface exposed to the exterior of the enclosure; and
 - the device comprising a mounting site to mount an integrated circuit, wherein the mounting site is on the interior surface, and a pattern of interconnects on the interior surface, wherein the pattern of interconnects is coupled with the mounting site to transmit signals for the integrated circuit.
54. (New) The apparatus of claim 53, further comprising a circuit board within the enclosure and interconnected with the pattern of interconnects.
55. (New) The apparatus of claim 53, further comprising at least one component located on the outside surface and coupled with the pattern of interconnects directly through the enclosure.
56. (New) The apparatus of claim 53, further comprising the integrated circuit coupled with the mount.
57. (New) The apparatus of claim 53, wherein the pattern of interconnects of the device is coupled with part of the enclosure.
58. (New) The apparatus of claim 57, wherein the part of the enclosure is composed of a non-conductive material.
59. (New) The apparatus of claim 57, wherein the part of the enclosure is to insulate independent paths of the pattern of interconnects.

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60. (New) The apparatus of claim 57, wherein the part of the enclosure is a plastic.